

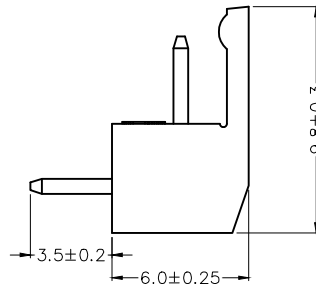
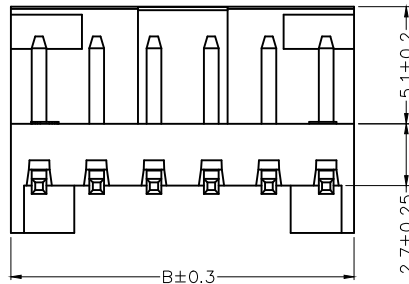
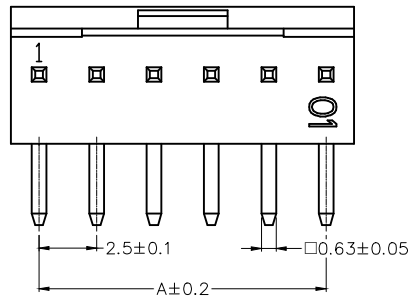
REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD

Electrical

Current Rating: 3.0A AC(rms)/DC  
 Voltage Rating: 250V AC(rms)/DC  
 Contact Resistance: 20 mΩ Max  
 Insulation Resistance: 1000 MΩ MIN  
 Withstanding Voltage: 1000V AC r.m.s  
 Temperature Range-Operating: -25°C~+85°C

Material and Plating

Housing: PA66( UL 94V-0)  
 Contact Pin: Brass  
 Plating: Tin Plated

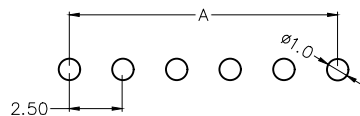


Circuits (n)	Part No.	Dimensions(mm)	
		A	B
2	FWF25032-S02B22BNB	2.50	5.00
3	FWF25032-S03B22BNB	5.00	7.50
4	FWF25032-S04B22BNB	7.50	10.00
5	FWF25032-S05B22BNB	10.00	12.50
6	FWF25032-S06B22BNB	12.50	15.00
7	FWF25032-S07B22BNB	15.00	17.50
8	FWF25032-S08B22BNB	17.50	20.00
9	FWF25032-S09B22BNB	20.00	22.50
10	FWF25032-S10B22BNB	22.50	25.00


Ordering Information

FWF 250 32 - S XX B 2 2 BN B  
 1 2 3 4 5 6 7 8 9 10

1   Category FWF-Wafer	2   Series Number 250-Pitch2.5mm	3   Distinction No. 32	4   Row Option S-Single Row	5   Circuits XX	6   Entry Angle B-90° Angle
7   Plating 2-Tin Plated	8   Material-Resin 2-PA66	9   Color-Resin BN-Brown	10   Packaging B-PE Bag		



Recommended P.C.Board Layout

THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY FRANK	DATE 08/APR/22	PART NO. FWF25032-SXXB22BNB	ITEM NO. FWF25032	 Leader Of Industry
	DESIGN UNITS Metric	X.±0.30	X.±5'	CHECKED BY CHERRY	DATE 08/APR/22	TITLE Wire to Board (Wafer) Pitch 2.5mm 90° Angle (DIP)	
SCALE 5:1	SIZE A4	X.XX±0.15	.XX±1'	DRAWN BY MATT	DATE 08/APR/22	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	